

What is claimed is :

1. A double sided chip package comprising:
 - a LOC lead frame having a plurality of leads, wherein each lead being from inside to outside divided into a supporting portion, an inner connecting portion and an outer connecting portion;
 - an upper chip having a plurality of bonding pads on its upper surface and being fixed to the top of the supporting portions of the leads with its bottom surface;
 - a bottom chip having a plurality of bonding pads and being fixed to the bottom of the supporting portions of the leads with its top surface;
 - a plurality of bonding wires electrically connecting the bonding pads of the upper chip to the inner connecting portions of the corresponding leads, and the bonding pads of the bottom chip to the inner connecting portions of the corresponding leads, respectively; and
 - a package body sealing the upper chip, the bottom chip, the bonding wires, the supporting portions and the inner connecting portions of the leads.
2. The double sided chip package in accordance with claim 1, further comprising a plurality of tapes fixing the upper chip and the bottom chip to the supporting portions of the leads.
3. The double sided chip package in accordance with claim 1, further comprising an epoxy compound fixing the upper chip and bottom chip on the supporting portions of the leads.
4. The double sided chip package in accordance with claim 1, wherein the supporting portions and the inner connecting portions of a plurality of leads are formed on the same plane.
5. The double sided chip package in accordance with claim 4, wherein the supporting portions and the inner connecting portions of a plurality of leads are formed on the same plane with equal distance to the upper chip and the bottom chip.

6. The double sided chip package in accordance with claim 1, wherein the LOC lead frame additionally includes at least a power lead comprising a supporting portion sandwiched between the upper chip and the bottom chip, and is perpendicular to the supporting portions of the other leads.